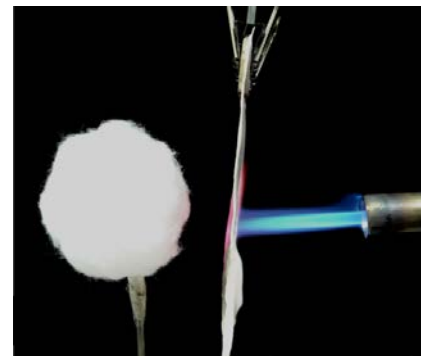
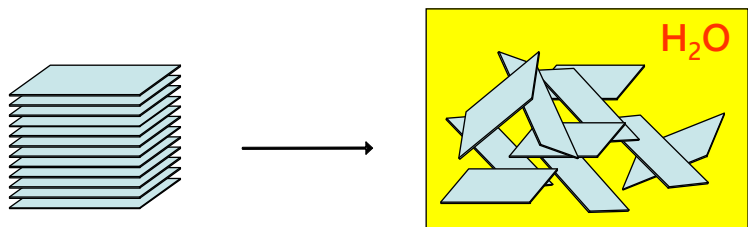


NSP Thin Films for Anti-heat-transfer and anti-flame-propagation

(by NSP self-piling coating technique; with composition of 60% silicates and 40% air-void Entrapped)

YC Wang, TK Huang, SH Tung, TM Wu and JJ Lin*, Scientific Reports, 2013, 3, Doi:10.1038/srep02621.

"Self-assembled Clay Films with A Platelet-void Multilayered Nanostructure and Flame-blocking Properties"

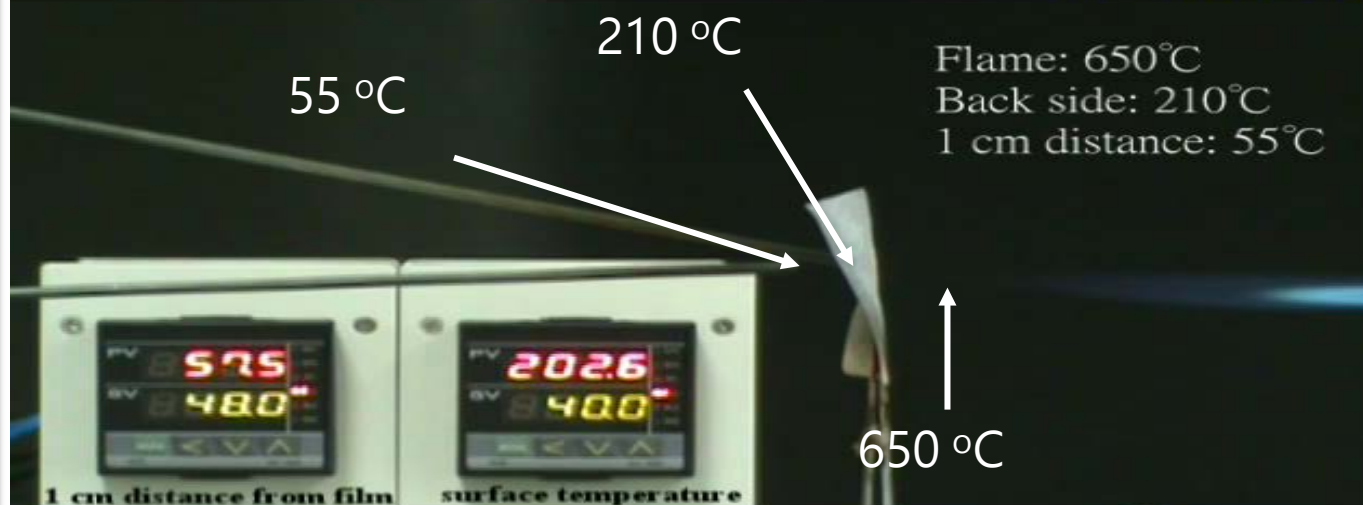


No penetration to z-axis!
No propagation over x,y-axis!

Anti-heat (low thermal conductivity)
(W/mK); air 0.025; Copper 386; Resin 0.2;
Calcium silicate 0.07-0.17)



Heat Shielding Property of NSP Film (30 μm) Normal Speed

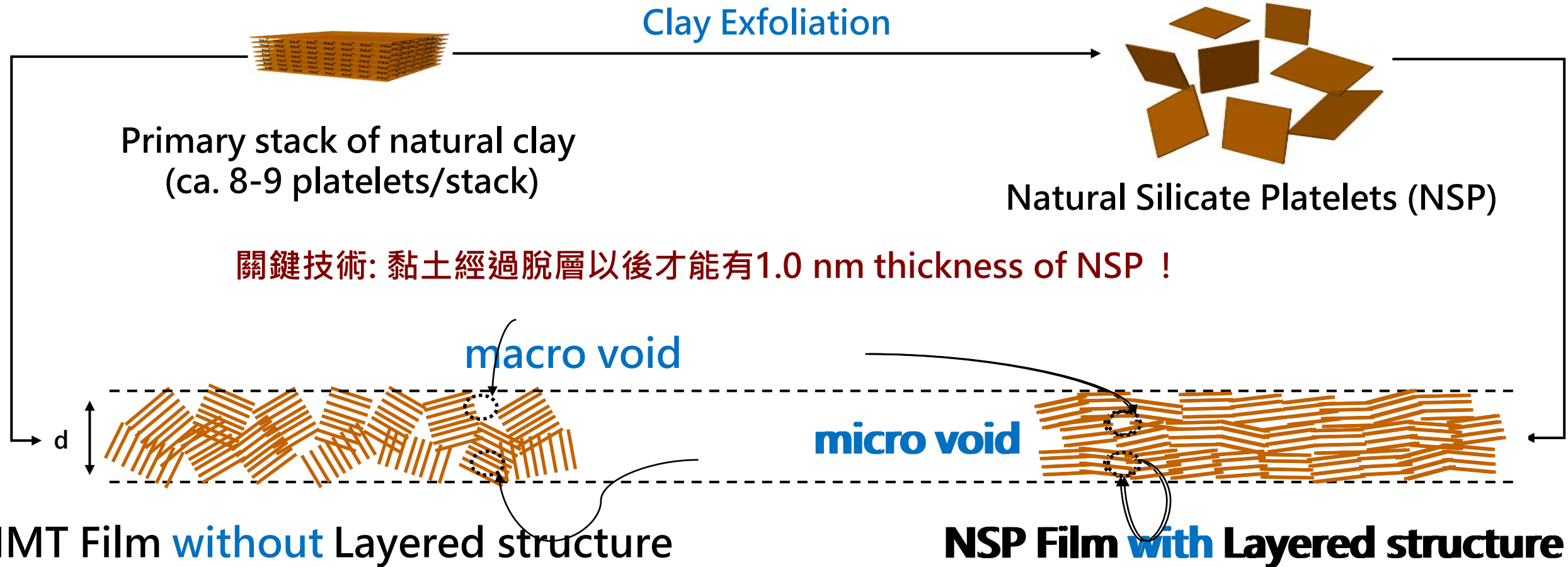


Scientific Report
(2013)

After One Hour

NSP --可自行排列(self-assembling)成薄膜 30 micrometers, 且內含有30-40 % air-void –

此奈米級多層結構之 真空vacuum層狀結構，為阻熱傳、阻火焰傳播之基本原理 --不同於傳統耐燃(有機磷或鹵素)材料



NSP thin-film with 40 % air void!
Enabling high efficient barrier for heat transfer and flame propagation